




<div>MICROCHIP</div>						Package Homogeneous Materials				
Semiconductor Device Type: M3X SPDIP-28-0.3in-MatteTin										
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	1656.43	(mg) Total	Mold Compound	% of Total Weight	79.35
Epoxy Resin	Trade Secret	Mold Compound	11.90	248.46	119026		Epoxy Resin	Trade Secret	15.00	
Hardner	Trade Secret	Mold Compound	9.52	198.77	95221		Hardner	Trade Secret	12.00	
Carbon Black	1333-86-4	Mold Compound	1.59	33.13	15870		Carbon Black	1333-86-4	2.00	
Metal Hydroxide	Trade Secret	Mold Compound	12.70	265.03	126961		Metal Hydroxide	Trade Secret	16.00	
Amorphous Silica	60676-86-0	Mold Compound	43.64	911.04	436428		Amorphous Silica	60676-86-0	55.00	
						Total 100.00				
Iron	7439-89-6	Lead Frame	0.02	0.46	219	218.15	(mg) Total	Lead Frame	% of Total Weight	10.45
Phosphorus	7723-14-0	Lead Frame	0.01	0.25	120					
Zinc	7440-66-6	Lead Frame	0.02	0.38	183					
Copper	7440-50-8	Lead Frame	9.14	190.88	91438					
Silver	7440-22-4	Lead Frame	1.25	26.18	12540					
Lead	7439-92-1	Lead Frame	0.00	0.00	1		Zinc	7440-66-6	0.17	
Silver	7440-22-4	Die Attach	0.60	12.53	6000		Copper	7440-50-8	87.50	
Epoxy Resin	9003-36-5	Die Attach	0.10	2.11	1013		Silver	7440-22-4	12.00	
t-Butyl phenyl glycidyl ether	3101-60-8	Die Attach	0.04	0.78	375		Lead	7439-92-1	0.00	
Phenolic Hardner	Trade Secret	Die Attach	0.01	0.16	75	Total 100.00				
Dicyandiamide	461-58-5	Die Attach	0.00	0.08	38	15.66	(mg) Total	Die Attach	% of Total Weight	0.75
Aluminum	7429-90-5	Die	0.03	0.54	256					
Titanium	7440-32-6	Die	0.00	0.04	21					
Tungsten	7440-33-7	Die	0.12	2.56	1225					
Silicon	7440-21-3	Die	7.35	153.42	73497					
Copper	7440-50-8	Wire Bond	0.19	4.01	1920		t-Butyl phenyl glycidyl ether	3101-60-8	5.00	
Palladium	7440-05-3	Wire Bond	0.01	0.13	60		Phenolic Hardner	Trade Secret	1.00	
Gold	7440-57-5	Wire Bond	0.00	0.02	10		Dicyandiamide	461-58-5	0.50	
Silver	7440-22-4	Wire Bond	0.00	0.00	2	Total 100.00				
Tin	7440-31-5	Lead Plating	1.25	26.08	12494	156.56	(mg) Total	Die	% of Total Weight	7.50
Lead	7439-92-1	Lead Plating	0.00	0.01	6					
Silicon Coated Polyester Film	Trade Secret	Lead Frame Tape	0.35	7.20	3451					
Polyimide Film	Trade Secret	Lead Frame Tape	0.13	2.61	1250					
Silicone Resin	Trade Secret	Lead Frame Tape	0.03	0.63	300					
2087.48 mg Total Mass			TOTALS:	100.00	2087.48	1,000,000	Total 100.00			
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